

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01508	100.0	0.25513
			Subtotal	0.01508	100	0.25513
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01293	5.0	0.2187
	Lead alloy	Silver (Ag)	7440-22-4	0.00388	1.5	0.06561
	Lead alloy	Lead (Pb)	7439-92-1	0.24175	93.5	4.08969
			Subtotal	0.25856	100	4.374
Die	Doped silicon	Silicon (Si)	7440-21-3	0.28374	100.0	4.8
			Subtotal	0.28374	100	4.8
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.23648	100.0	4.00047
			Subtotal	0.23648	100	4.00047
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.06514	0.1	1.102
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01954	0.03	0.3306
	Copper alloy	Copper (Cu)	7440-50-8	65.0569	99.87	1100.5674
			Subtotal	65.14158	100	1102
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.13418	100.0	2.27
			Subtotal	0.13418	100	2.27
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.52687	4.5	25.83
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.39304	10.0	57.4
	Filler	Silica fused	60676-86-0	25.44778	75.0	430.5
	Metal hydroxide	Metal hydroxide		3.39304	10.0	57.4
	Carbon Black	Carbon black	1333-86-4	0.16965	0.5	2.87
			Subtotal	33.93038	100	574
			Total	100	100	1691.6996

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.